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PATENT APPLICATION

ATTORNEY DOCKET NO.

200312670-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s):

Neal W. Meyer et al

Confirmation No.: 2065

Application No.: 10/822064

Examiner: unassigned

Apr 08, 2004 Filing Date:

Group Art Unit:

Title: Bonding An Interconnect To A Circuit Device And Related Devices

Mail Stop Amendment Commissioner For Patents PO Box 1450

Alexandria, VA 22313-1450	
INFORMATION DISCLOSE	<u>IRE STATEMENT</u>
This Information Disclosure Statement is submitted: under 37 CRF 1.97 (b), or (Within three months of filing national application; or date of first action on the merits; whichever occurs la	date of entry of national application; or before mailing set)
under 37 CRF 1.97 (c), together with either a: Statement under 37 CFR 1.97 (e), or a \$180 fee under 37 CFR 1.17 (p), or (After the CFR 1.97 (b) time period, but before final	action or notice of allowance, whichever occurs first)
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Applicant(s) submit herewith form PTO 1449 - Information Dispatents, publications or other information of which applicant(s) at the examination of this application and for which there may be a contract of the examination o	re aware, which applicant(s) believe(s) may be material to
A concise explanation of the relevance of foreign language language information listed on PTO Form 1449, as present 1.56 (c) most knowledgeable about the content is given on cited in a search report or other action by a foreign pate language version of the search report or action which indicated on form PTO 1449 and is enclosed.	ntly understood by the individual(s) designated in 37 CFR the attached sheet, or where a foreign language patent is ent office in a counterpart foreign application, an english
It is requested that the information disclosed herein be made of re	cord in this application.
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450	Respectfully submitted, Neal W. Meyer et al
Date of Deposit: 1 5 0 6 OR	Donald J. Coulman
I hereby certify that this paper is being transmitted to the Patent and Trademark Office facsimile number (571) 273-8300 Date of facsimile:	Attorney/Agent for Applicant(s) Reg No.: 50,406
Typed Name: Donald J. Coulman Signature:	Date : 1/6/0 6 Telephone : 541 715 1694
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Sheet 1

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

<u>l of</u> 2

Application Number	10/822064			
Filing Date	Apr 8, 2004			
First Named Inventor	Neal W. Meyer			
Art Unit				
Examiner Name	unassigned			
Attorney Docket Number	200312670-1			

	U. S. PATENT DOCUMENTS							
Examiner Initials*	Cite No.1	Document Number Number-Kind Code ^{2 (# known)}	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear			
/RC/		^{US-} 2003/016503	01-23-2003	Gerd				
		^{US-} 5,233,134	08-03-1993	Hirai				
V		^{US-} 2003/042587	03-06-2003	Tsung-Jen				
/RC/		^{US-} 6,054,371	04-25-2000	Tsuchiaki				
		US-						
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FOREIGN PATENT DOCUMENTS							
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Examiner Signature	/Rick Chang/	Date Considered	11/25/2007

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Substitute for form 1449/PTO		Complete if Known			
Jubauta	te 10(10(1)) 1445/1 10			Application Number	10/822064
INF	ORMATION	DIS	CLOSURE	Filing Date	Apr 8, 2004
STATEMENT BY APPLICANT		First Named Inventor	Neal W. Meyer		
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	(OSE as many sine		eccessury)	Examiner Name	unassigned
Sheet	2	of	2	Attorney Docket Number	200312670-1

NON PATENT LITERATURE DOCUMENTS						
Examiner Initials*	Examiner Cite Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of					
/RC/	/RC/ SHIGETOU, "Room temperature direct bonding of CMP-Cu film for bumpless interconnection", Electronic Components & Tech Conf, May 29, 2001, pgs 755-760.					
/RC	Ý	SUGA, "Bump-less interconnect for next generation system packaging", Electronic Components & Tech Conf, May 29, 2001, pgs 1003-1008.				
/RC/		SUGA, "Surface activated bonding for new flip chip and bumpless interconnect systems", Electronic Components & Tech Conf, May 29, 2001, pgs 105-111.				

Examiner	Dick Changl	Date	
Signature	/Rick Chang/	Considered	11/25/2007

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